

MIC2514

Integrated High-Side Switch

Features

- · MOSFET On-Resistance
 - 1.5Ω Typical at 5V
 - 0.95Ω Typical at 12V
- 3V to 13.5V Input
- 25 µA Typical On-State Supply Current at 5V
- <1 µA Typical Off-State Supply Current at 5V
- · Current Limit
- · Thermal Shutdown
- · Slow Turn-On

Applications

· 3.3V to 13.5V Power Management

General Description

The MIC2514 is an integrated high-side power switch that consists of a TTL-compatible input and protected P-channel MOSFET. The MIC2514 can be used instead of a separate high-side driver and MOSFET in many low voltage applications.

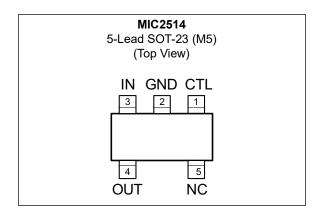
The MIC2514 switches voltage ranging from 3V to 13.5V and delivers more than 400 mA continuous current. A slow turn-on feature prevents high inrush current when switching capacitive loads. The internal control circuitry is powered from the unswitched 3V to 13.5V input.

Current limiting is internally fixed at approximately 1.9A and requires no external components.

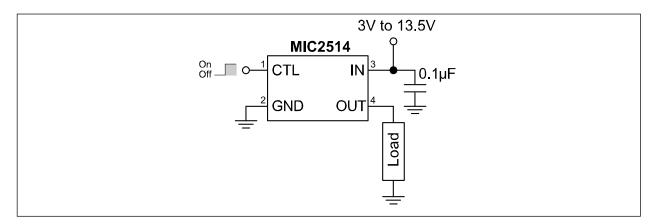
Thermal shutdown turns off the output if the die temperature exceeds approximately 170°C .

The MIC2514 is available in the 5-lead SOT-23-5 package with a temperature range of -40°C to +85°C.

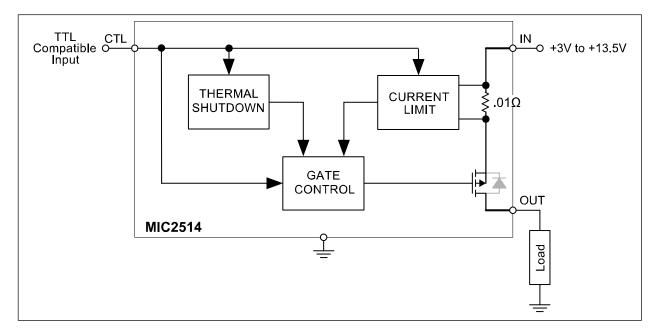
Package Type



Typical Application Circuit



Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage (V _{IN})	+20V
	Internally Limited
	-0.3V to +15V

Operating Ratings ‡

Supply Voltage (V _{IN})	+3.0V to +13.5V
Control Input (V _{CTRL})0.3V to V _{IN}

[†] Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

‡ Notice: The device is not guaranteed to function outside its operating ratings.

Note: Device is ESD sensitive. Handling precautions are recommended.

ELECTRICAL CHARACTERISTICS

 V_{IN} = 5V; T_A = 25°C, **bold** values valid for -40°C ≤ T_A ≤ +85°C, unless noted. Note 1

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
		_	0.6	10		V _{CTL} = logic 0, V _{IN} = 5V
		_	2.0	25		V _{CTL} = logic 0, V _{IN} = 13.5V
Supply Current	I _{CC}	_	10	20	μA	V _{CTL} = logic 1, V _{IN} = 3V
			25	40		V _{CTL} = logic 1, V _{IN} = 5V
		_	95	200		V _{CTL} = logic 1, V _{IN} = 13.5V
		0	_	0.79		$V_{CTL} = logic 0, 3V \le V_{IN} \le 13.5V$
Control Input Voltage	V _{CTL}	8.0	1.45	2.0	V	$V_{CTL} = logic 1, 3V \le V_{IN} \le 5V$
		8.0	1.65	2.3		V _{CTL} = logic 1, 5V ≤ V _{IN} ≤ 13.5V
		_	2.4	4.5	Ω	V _{IN} = 3V
		_	1.5	2.4		V _{IN} = 5V
Output MOSFET Resistance				2.7		VIN - 3V
		_	0.95	1.5		V _{IN} = 12V
		_		1.7		VIN - 12 V
Current Limit Threshold	I _{LIM}	_	0.5	1.5	Α	V _{IN} = 3V
		1.0	1.4	2.0		V _{IN} = 5V
		1.2	1.9	2.5		V _{IN} = 12V

Note 1: Device production tested at 25°C, but device is ensured over indicated temperature range.

MIC2514

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions	
Temperature Ranges							
Ambient Temperature Range	T _A	-40	_	+85	°C	_	
Storage Temperature Range	T _S	-65	_	+150	°C	_	
Package Thermal Resistances							
Thermal Decistance F.I.d SOT 22	θ_{JA}	_	220	_	°C/W	_	
Thermal Resistance, 5-Ld SOT-23	θ_{JC}	_	130	_	°C/W	_	

2.0 TYPICAL PERFORMANCE CURVES

Note:

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

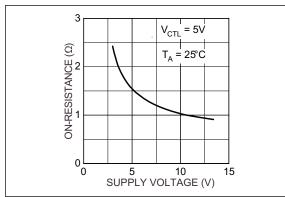


FIGURE 2-1: On-Resistance vs. Supply Voltage.

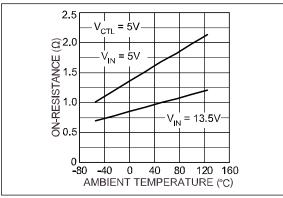


FIGURE 2-2: On-Resistance vs Temperature.

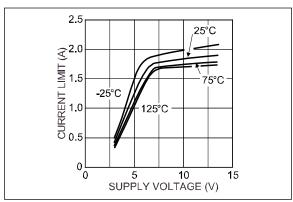


FIGURE 2-3: Current Limit vs. Supply Voltage.

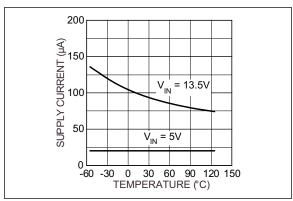


FIGURE 2-4: On-State Supply Current vs. Temperature.

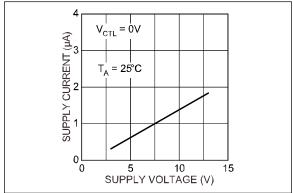


FIGURE 2-5: Off-State Current Supply vs. Supply Voltage.

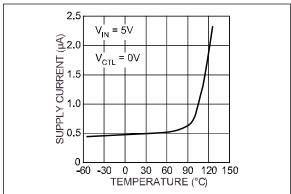


FIGURE 2-6: Off-State Supply Current vs. Temperature.

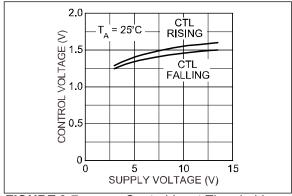


FIGURE 2-7: Supply Voltage.

Control Input Threshold vs.

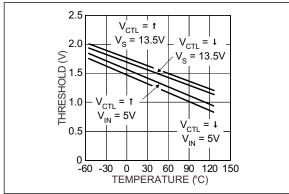


FIGURE 2-8: Temperature.

Control Input Threshold vs.

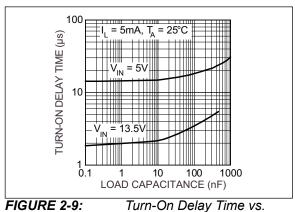


FIGURE 2-9: Load Capacitance.

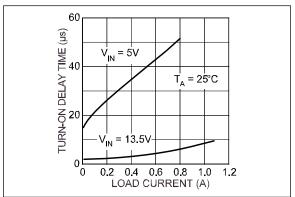


FIGURE 2-10: Load Current.

Turn-On Delay Time vs.

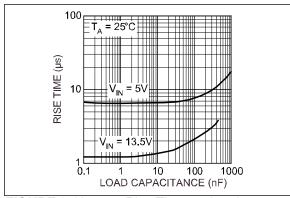


FIGURE 2-11: Capacitance.

Rise Time vs. Load

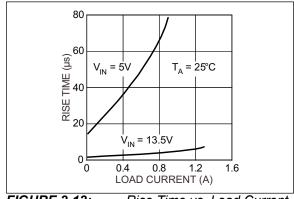


FIGURE 2-12:

Rise Time vs. Load Current.

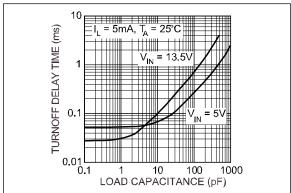


FIGURE 2-13: Turn-Off Delay Time vs. Load Capacitance.

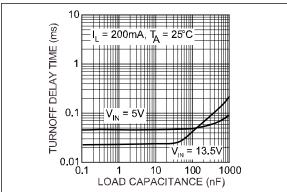


FIGURE 2-14: Turn-Off Delay Time vs. Load Capacitance.

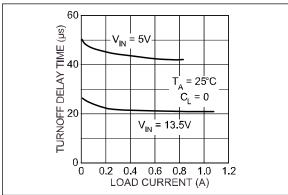


FIGURE 2-15: Turn-Off Delay Time vs. Load Current.

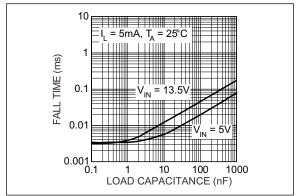


FIGURE 2-16: Fall Time vs. Load Capacitance.

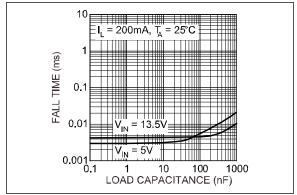


FIGURE 2-17: Fall Time vs. Load Capacitance.

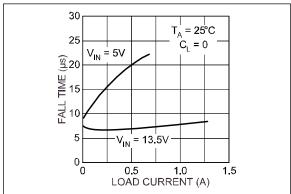


FIGURE 2-18: Fall Time vs. Load Current.

MIC2514

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	CTL	Control (Input): Non-inverting TTL compatible control input. High = on, low = off.
2	GND	Ground.
3	IN	Supply Input: Output MOSFET source. Also supplies the IC's internal circuitry. Connect to supply.
4	OUT	Switch Output: Output MOSFET drain. Connect to switched side of load.
5	NC	Not internally connected. Connect to ground plane for lowest package thermal resistance.

4.0 FUNCTIONAL DESCRIPTION

The MIC2514 is a non-inverting high-side switch. A logic-high control input turns on the output transistor, and a logic-low turns off the output transistor. Fault conditions turn off the output transistor.

4.1 Control Input

Applying a logic-high input to CTL (control input) activates the thermal shutdown and gate control circuits. If there are no fault conditions, the output MOSFET turns on.

4.2 Gate Control

The gate control circuit applies the supply voltage to the output MOSFET gate, turning it off, or forces the MOSFET gate below the supply voltage, turning it on, as determined by CTL and thermal shutdown.

4.3 Input and Output

IN (input) is the supply connection to the logic circuitry and the source of the output MOSFET. OUT (output) is the drain of the output MOSFET. In a typical circuit; current flows through the switch from IN to OUT toward the load.

The output MOSFET has an intrinsic body diode which will conduct if OUT is forced to a higher voltage than IN.

4.4 Thermal Shutdown

Thermal shutdown turns off the output MOSFET if the die temperature exceeds approximately 170°C. Thermal shutdown releases the output after the die temperature decreases 10°C.

4.5 Current Limit

The current limit is preset internally. The preset level prevents damage to the output MOSFET but allows a typical current of 1.9A through the output MOSFET for the MIC2514. This current limit is sufficient to protect the bond wire and the output device from instantaneous high current. Package thermal ratings and power dissipation should be considered when determining safe continuous operating current. Output current is monitored by sensing the voltage drop across the output MOSFET source metal resistance.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

XX...XLegend: Product code or customer-specific information Year code (last digit of calendar year) ΥY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code Pb-free JEDEC® designator for Matte Tin (Sn) (e3) This package is Pb-free. The Pb-free JEDEC designator (@3) can be found on the outer packaging for this package. •, ▲, ▼ Pin one index is identified by a dot, delta up, or delta down (triangle mark). In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo. Underbar (_) and/or Overbar (¯) symbol may not be to scale.

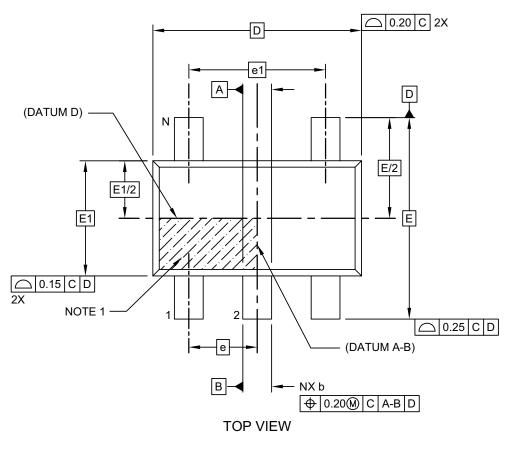
Note: If the full seven-character YYWWNNN code cannot fit on the package, the following truncated codes are used based on the available marking space:

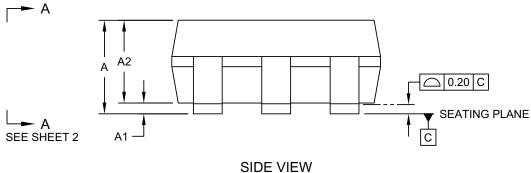
6 Characters = YWWNNN; 5 Characters = WWNNN; 4 Characters = WNNN; 3 Characters = NNN;

2 Characters = NN; 1 Character = N

5-Lead Plastic Small Outline Transistor (6BX) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

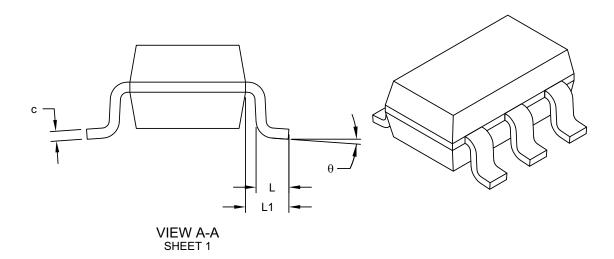




Microchip Technology Drawing C04-091-6BX Rev H Sheet 1 of 2

5-Lead Plastic Small Outline Transistor (6BX) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS					
Dimension	MIN	NOM	MAX			
Number of Pins	N		5			
Pitch	е		0.95 BSC			
Outside lead pitch	e1	1.90 BSC				
Overall Height	Α	0.90	1	1.45		
Molded Package Thickness	A2	0.89	-	1.30		
Standoff	A1	0.15				
Overall Width	Е	2.80 BSC				
Molded Package Width	E1	1.60 BSC				
Overall Length	D	2.90 BSC				
Foot Length	L	0.30	-	0.60		
Footprint	L1	0.60 REF				
Foot Angle	θ	0°	-	10°		
Lead Thickness	С	0.08 - 0.26				
Lead Width	b	0.20 - 0.51				

Notes:

- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M

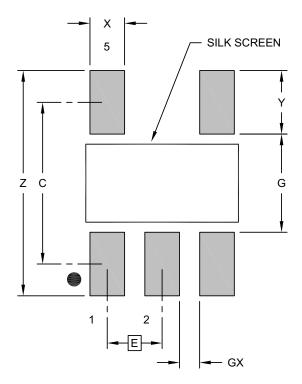
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-091-6BX Rev H Sheet 2 of 2

5-Lead Plastic Small Outline Transistor (6BX) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	MIN	NOM	MAX	
Contact Pitch	Е	0.95 BSC		
Contact Pad Spacing	O		2.80	
Contact Pad Width (X5)	X			0.60
Contact Pad Length (X5)	Υ			1.10
Distance Between Pads	G	1.70		
Distance Between Pads	GX	0.35		
Overall Width	Z			3.90

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2091-6BX Rev H



NOTES:

APPENDIX A: REVISION HISTORY

Revision A (May 2024)

- Converted Micrel document MIC2514 to Microchip data sheet DS20006898A.
- Minor text changes throughout.



NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

Part Number	<u>x</u>	XX	- <u>XX</u>	Examples:	
Device	Temperature Range	Package	Media Type	a) MIC2514YM5-TF	R: MIC2514, -40°C to +85°C Temp. Range, 5-Lead SOT-23,
Device:	MIC2514:	Integrated High-Side Switch	1		3,000/Reel
Temperature Range:	Y =	-40°C to +85°C		catalo is us	and Reel identifier only appears in the og part number description. This identifier ed for ordering purposes and is not
Package:	M5 =	5-Lead SOT-23		your I	d on the device package. Check with Microchip Sales Office for package avail- with the Tape and Reel option.
Media Type:	TR =	3,000/Reel			



NOTES:

Note the following details of the code protection feature on Microchip products:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
- Microchip values and aggressively protects its intellectual property rights. Attempts to breach the code protection features of Microchip product is strictly prohibited and may violate the Digital Millennium Copyright Act.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not
 mean that we are guaranteeing the product is "unbreakable" Code protection is constantly evolving. Microchip is committed to
 continuously improving the code protection features of our products.

This publication and the information herein may be used only with Microchip products, including to design, test, and integrate Microchip products with your application. Use of this information in any other manner violates these terms. Information regarding device applications is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. Contact your local Microchip sales office for additional support or, obtain additional support at https://www.microchip.com/en-us/support/design-help/client-support-services.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE, OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDIRECT, SPECIAL, PUNITIVE, INCIDENTAL, OR CONSEQUENTIAL LOSS, DAMAGE, COST, OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION.

Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

Trademarks

The Microchip name and logo, the Microchip logo, Adaptec, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, CryptoMemory, CryptoRF, dsPlC, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, ClockWorks, The Embedded Control Solutions Company, EtherSynch, Flashtec, Hyper Speed Control, HyperLight Load, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, TimeCesium, TimeHub, TimePictra, TimeProvider, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, Clockstudio, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, EyeOpen, GridTime, IdealBridge, IGaT, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, IntelliMOS, Inter-Chip Connectivity, JitterBlocker, Knob-on-Display, MarginLink, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mSiC, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, Power MOS IV, Power MOS 7, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SmartHLS, SMART-I.S., storClad, SQI, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, Trusted Time, TSHARC, Turing, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2024, Microchip Technology Incorporated and its subsidiaries.

All Rights Reserved.

ISBN: 978-1-6683-4537-5

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.



Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199

Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://www.microchip.com/

support Web Address:

www.microchip.com

Atlanta Duluth, GA

Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Novi. MI

Tel: 248-848-4000

Houston, TX

Tel: 281-894-5983 Indianapolis

Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

San Jose, CA Tel: 408-735-9110 Tel: 408-436-4270

Canada - Toronto Tel: 905-695-1980 Fax: 905-695-2078

ASIA/PACIFIC

Australia - Sydney Tel: 61-2-9868-6733

China - Beijing Tel: 86-10-8569-7000

China - Chengdu Tel: 86-28-8665-5511

China - Chongqing Tel: 86-23-8980-9588

China - Dongguan Tel: 86-769-8702-9880

China - Guangzhou Tel: 86-20-8755-8029

China - Hangzhou Tel: 86-571-8792-8115

China - Hong Kong SAR Tel: 852-2943-5100

China - Nanjing Tel: 86-25-8473-2460

China - Qingdao Tel: 86-532-8502-7355

China - Shanghai Tel: 86-21-3326-8000

China - Shenyang Tel: 86-24-2334-2829

China - Shenzhen Tel: 86-755-8864-2200

China - Suzhou

Tel: 86-186-6233-1526 China - Wuhan

Tel: 86-27-5980-5300

China - Xian Tel: 86-29-8833-7252

China - Xiamen Tel: 86-592-2388138

China - Zhuhai Tel: 86-756-3210040

ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444

India - New Delhi Tel: 91-11-4160-8631

India - Pune Tel: 91-20-4121-0141

Japan - Osaka Tel: 81-6-6152-7160

Japan - Tokyo

Tel: 81-3-6880- 3770 Korea - Daegu

Tel: 82-53-744-4301

Korea - Seoul Tel: 82-2-554-7200

Malaysia - Kuala Lumpur Tel: 60-3-7651-7906

Malaysia - Penang Tel: 60-4-227-8870

Philippines - Manila Tel: 63-2-634-9065

Singapore Tel: 65-6334-8870

Taiwan - Hsin Chu Tel: 886-3-577-8366

Taiwan - Kaohsiung Tel: 886-7-213-7830

Taiwan - Taipei Tel: 886-2-2508-8600

Thailand - Bangkok Tel: 66-2-694-1351

Vietnam - Ho Chi Minh Tel: 84-28-5448-2100

EUROPE

Austria - Wels Tel: 43-7242-2244-39

Fax: 43-7242-2244-393

Denmark - Copenhagen Tel: 45-4485-5910 Fax: 45-4485-2829

Finland - Espoo Tel: 358-9-4520-820

France - Paris Tel: 33-1-69-53-63-20

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Garching Tel: 49-8931-9700

Germany - Haan Tel: 49-2129-3766400

Germany - Heilbronn Tel: 49-7131-72400

Germany - Karlsruhe Tel: 49-721-625370

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Germany - Rosenheim Tel: 49-8031-354-560

Israel - Hod Hasharon Tel: 972-9-775-5100

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Padova Tel: 39-049-7625286

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Norway - Trondheim Tel: 47-7288-4388

Poland - Warsaw Tel: 48-22-3325737

Romania - Bucharest Tel: 40-21-407-87-50

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Gothenberg Tel: 46-31-704-60-40

Sweden - Stockholm Tel: 46-8-5090-4654

UK - Wokingham Tel: 44-118-921-5800 Fax: 44-118-921-5820